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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/781,964	02/19/2004	Christophe Chevallier	400.184US07	4423	
7590 12/28/2004			EXAMINER		
Leffert Jay & Polglaze, P.A.			LEVIN, NAUM B		
P.O. Box 581009 Minneapolis, MN 55458-1009			ART UNIT	PAPER NUMBER	
			2825		
			DATE MAILED: 12/28/2004		

Please find below and/or attached an Office communication concerning this application or proceeding.

				<del></del>			
	•	Applica	ation No.	Applicant(s)	Applicant(s)		
		10/781	10/781,964 CHEVALLIER		ΓAL.		
	Office Action Summary	Examir	ner	Art Unit			
		Naum I	3 Levin	2825			
Period for	The MAILING DATE of this commu Reply	nication appears on	the cover sheet	with the correspondence a	ddress		
THE M/ - Extension after Silver if the period of the perio	RTENED STATUTORY PERIOD IN AILING DATE OF THIS COMMUNIONS of time may be available under the provision (6) MONTHS from the mailing date of this comprised for reply specified above, the maximum is to reply within the set or extended period for reply received by the Office later than three months patent term adjustment. See 37 CFR 1.704(b).	NICATION. us of 37 CFR 1.136(a). In no umunication. (30) days, a reply within the statutory period will apply and uy will, by statute, cause the	event, however, may statutory minimum of t d will expire SIX (6) Mo application to become	a reply be timely filed hirty (30) days will be considered time DNTHS from the mailing date of this ABANDONED (35 U.S.C. § 133).	ety. communication.		
Status							
1)⊠ R	esponsive to communication(s) file	led on 19 February	2004.				
·							
•	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.						
Dispositio	n of Claims						
4a 5)□ C 6)⊠ C 7)□ C	<ul> <li>✓ Claim(s) 1-19 is/are pending in the application.</li> <li>4a) Of the above claim(s) is/are withdrawn from consideration.</li> <li>☐ Claim(s) is/are allowed.</li> <li>✓ Claim(s) 1-19 is/are rejected.</li> </ul>						
Application	n Papers						
10)⊠ TI A R	ne specification is objected to by the drawing(s) filed on 19 February pplicant may not request that any objected the oath or declaration is objected to	$\frac{\sqrt{2004}}{\sqrt{2004}}$ is/are: a) $\boxed{\square}$ a ection to the drawing (so the correction is required.	s) be held in abey uired if the drawir	ance. See 37 CFR 1.85(a). ng(s) is objected to. See 37 C	DFR 1.121(d).		
Priority un	der 35 U.S.C. § 119						
a)□ 1 2 3	cknowledgment is made of a claim  All b) Some * c) None of:  Certified copies of the priority  Copies of the certified copies  application from the Internative the attached detailed Office active.	y documents have by documents have be of the priority docu	een received. een received in ments have bee Rule 17.2(a)).	Application No en received in this Nationa	ıl Stage		
Attachmant/-	1						
Attachment(s	) of References Cited (PTO-892)		4) Interview	v Summary (PTO-413)			
2) D Notice o	of Draftsperson's Patent Drawing Review (		Paper No	o(s)/Mail Date			
	tion Disclosure Statement(s) (PTO-1449 o lo(s)/Mail Date <u>02/19/04</u> .	r PTO/SB/08)	5)  Notice of Other: _	f Informal Patent Application (PT 	O-152)		

Art Unit: 2825

### **DETAILED ACTION**

### Claim Objections

1. Claims 1, 12 and 16 are objected to:

the recitation of "line width parameter" and "actual line width" are not clear to what applicants intend to mean;

# Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- 2. Claims 1 and 3-11 are rejected under 35 U.S.C. 102(b) as being unpatentable by Majors (US Patent 5,581,475).

As to claim 1 Majors discloses method for interactively tailoring topography of integrated circuit layout in accordance with electromigration model-based minimum width metal and contact/via rules including:

A method of design rule checking an integrated circuit, comprising (Abstract):

identifying any line (interconnect metal) having a line width marker (layout highlights) and line width parameter (topology parameters/dimensions of interconnect metal/minimum device geometry values Wmin) (col.21,ll.25-39; col.2,ll.52-61; col.10,ll.45-67);

Application/Control Number: 10/781,964 Page 3

Art Unit: 2825

extracting (selecting/deriving) each line having a line width marker (col.11,ll.1-39; col.18,ll.53-67; col.19,ll.1-11);

determining the line width parameter for each extracted line (col.11,ll.40-67; col.12,ll.1-12); and

comparing the line width parameter with an actual line width for the line (col.22,II.21-43).

## As to claims 3-11 Majors recites:

- (3) The method of claim 1, and further comprising generating an error condition when the actual line width for the line is less than the line width parameter (col.22, II.34-56);
- (4) The method of claim 1, and further comprising indicating (highlighting error regions) or recording an error (col.22, II.34-56; col.23, II.14-35);

when the actual line width for the line is less than the line width parameter.

- (5) The method of claim 1, wherein each line having a width marker has a width greater (exceeds minimum width) than a minimum width for that line (col.23, II.14-35);
- (6) The method of claim 1, wherein identifying any line comprises identifying any line in a schematic (col.2, II.52-61; col.10, II.45-67);
- (7) The method of claim 1, wherein each extracted line has a line width marker in a layout (col.11, II.1-39);
- (8) The method of claim 1, wherein each extracted line has a line width marker in a line width layer (col.10, II.45-67; col.11, II.1-39);

Application/Control Number: 10/781,964 Page 4

Art Unit: 2825

(9) The method of claim 1, wherein the line width parameter represents a minimum line width for the line associated with that line width parameter (col.10, II.45-67);

- (10) The method of claim 1, and further comprising extracting a width for each extracted line (col.23, II.14-35);
- (11) The method of claim 1, wherein determining the line width parameter for each extracted line comprises extracting the line width marker and line width parameter for each extracted line (col.11, II.40-67; col.12, II.1-12).

### Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

- (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 3. Claims 2 and 12-19 are rejected under 35 U.S.C. 103(a) as being unpatentable over Majors in view of Suzuki (US Patent 5,706,295).

As to claims 12, 16 and 2 Majors discloses:

(12) A method of design rule checking an integrated circuit, comprising (Abstract):

identifying any line (interconnect metal) having a line width marker (layout highlights) and line width parameter (topology parameters/dimensions of interconnect

Art Unit: 2825

metal/minimum device geometry values Wmin) (col.21,ll.25-39; col.2,ll.52-61; col.10,ll.45-67);

extracting (selecting/deriving) each line having a line width marker (col.11,ll.1-39; col.18,ll.53-67; col.19,ll.1-11);

determining the line width parameter for each extracted line (col.11,ll.40-67; col.12,ll.1-12); and

comparing the line width parameter with an actual line width for the line (col.22,ll.21-43);

(16) A method of design rule checking an integrated circuit, comprising (Abstract):

identifying any line (interconnect metal) having a line width marker (layout highlights) and line width parameter (topology parameters/dimensions of interconnect metal/minimum device geometry values Wmin) (col.21,II.25-39; col.2,II.52-61; col.10,II.45-67);

extracting (selecting/deriving) each line having a line width marker (col.11,ll.1-39; col.18,ll.53-67; col.19,ll.1-11);

determining the line width parameter for each extracted line (col.11,ll.40-67; col.12,ll.1-12); and

comparing the line width parameter with an actual line width for the line (col.22,II.21-43).

Art Unit: 2825

With respect to claims 12, 16 and 2 Majors teaches the features above but lacks a method of design rule checking an integrated circuit, wherein steps of extracting or comparing exclude lines near or above a transistor.

Suzuki describes a method of checking design rules for semiconductor integrated circuit including:

a method of design rule checking an integrated circuit, wherein steps of extracting or comparing exclude (except) lines near or above a transistor (interconnection data 203 across the specified-region data 801, positioned on the mask pattern data of the transistor that is not included in the region-specified mask pattern data) (Abstract; col.7, II.64-67; col.8, II.1-41).

It would have been obvious to a person of ordinary skills in the art at the time the invention was made to employ Suzuki's teaching regarding the method of design rule checking an integrated circuit, wherein steps of extracting or comparing exclude (except) lines near or above a transistor and use it in Majors' invention to improve checking of layout line width in IC layouts by decreasing design data value, thereby increasing speed of the IC design verification process.

As to claims 13-15 and 17-19 Majors teaches the features above but lacks a method of design rule checking an integrated circuit, wherein steps of extracting or comparing exclude lines near or above a transistor.

Suzuki describes a method of checking design rules for semiconductor integrated circuit including:

Art Unit: 2825

a method of design rule checking an integrated circuit, wherein steps of extracting or comparing exclude (except) lines near or above a transistor (interconnection data 203 across the specified-region data 801, positioned on the mask pattern data of the transistor that is not included in the region-specified mask pattern data) (Abstract; col.7, II.64-67; col.8, II.1-41).

It would have been obvious to a person of ordinary skills in the art at the time the invention was made to employ Suzuki's teaching regarding the method of design rule checking an integrated circuit, wherein steps of extracting or comparing exclude (except) lines near or above a transistor and use it in Majors' invention to improve checking of layout line width in IC layouts by decreasing design data value, thereby increasing speed of the IC design verification process.

#### Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Naum B Levin whose telephone number is 571-272-1898. The examiner can normally be reached on M-F (8:00-4:30).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Matthew S Smith can be reached on 571-272-1907. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Art Unit: 2825

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

NL

Muando THUAN DO Primary examiner 12/23/2004